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(12) **United States Design Patent**
Podubni

(10) **Patent No.:** **US D826,189 S**

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- (54) **MODULAR CIRCUIT BOARD**
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- (73) Assignee: **TinyPCB, Inc.**
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- (51) **LOC (11) Cl.** **13-03**
- (52) **U.S. Cl.**
USPC **D13/182**
- (58) **Field of Classification Search**
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361/720, 728, 736, 748, 751, 752, 760,
361/761, 807; 439/55, 65, 68, 76.1, 92,
439/93, 95
CPC H05K 3/00; H05K 3/30; H05K 3/301;
H05K 3/303; H05K 3/34; H05K 3/3405;
H05K 3/341; H05K 3/36; H05K 3/361;
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H05K 1/183; H05K 1/184; H05K 1/189;
H05K 1/00
See application file for complete search history.

- 4,715,928 A * 12/1987 Hamby H05K 3/4691
156/150
- D319,045 S * 8/1991 Hasegawa D13/182
- D319,629 S * 9/1991 Hasegawa D13/182
- D319,814 S * 9/1991 Hasegawa D13/182
- D397,093 S * 8/1998 Kim D13/182
- 5,895,967 A * 4/1999 Stearns H01L 23/3128
257/691
- D429,704 S * 8/2000 Kang D13/182
- 6,121,554 A * 9/2000 Kamikawa H05K 1/113
174/255
- D440,209 S * 4/2001 Kang D13/182
- D442,149 S * 5/2001 Kang D13/182
- D442,150 S * 5/2001 Kang D13/182
- D442,567 S * 5/2001 Kang D13/182
- D457,146 S * 5/2002 Yamamoto D13/182
- 6,418,030 B1 * 7/2002 Yamaguchi H01L 23/24
257/698
- 6,462,570 B1 10/2002 Price et al.
- D466,093 S * 11/2002 Ebihara D13/182
- D471,167 S * 3/2003 Ebihara D13/182

(Continued)

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(57) **CLAIM**

The ornamental design for a modular circuit board, as shown and described.

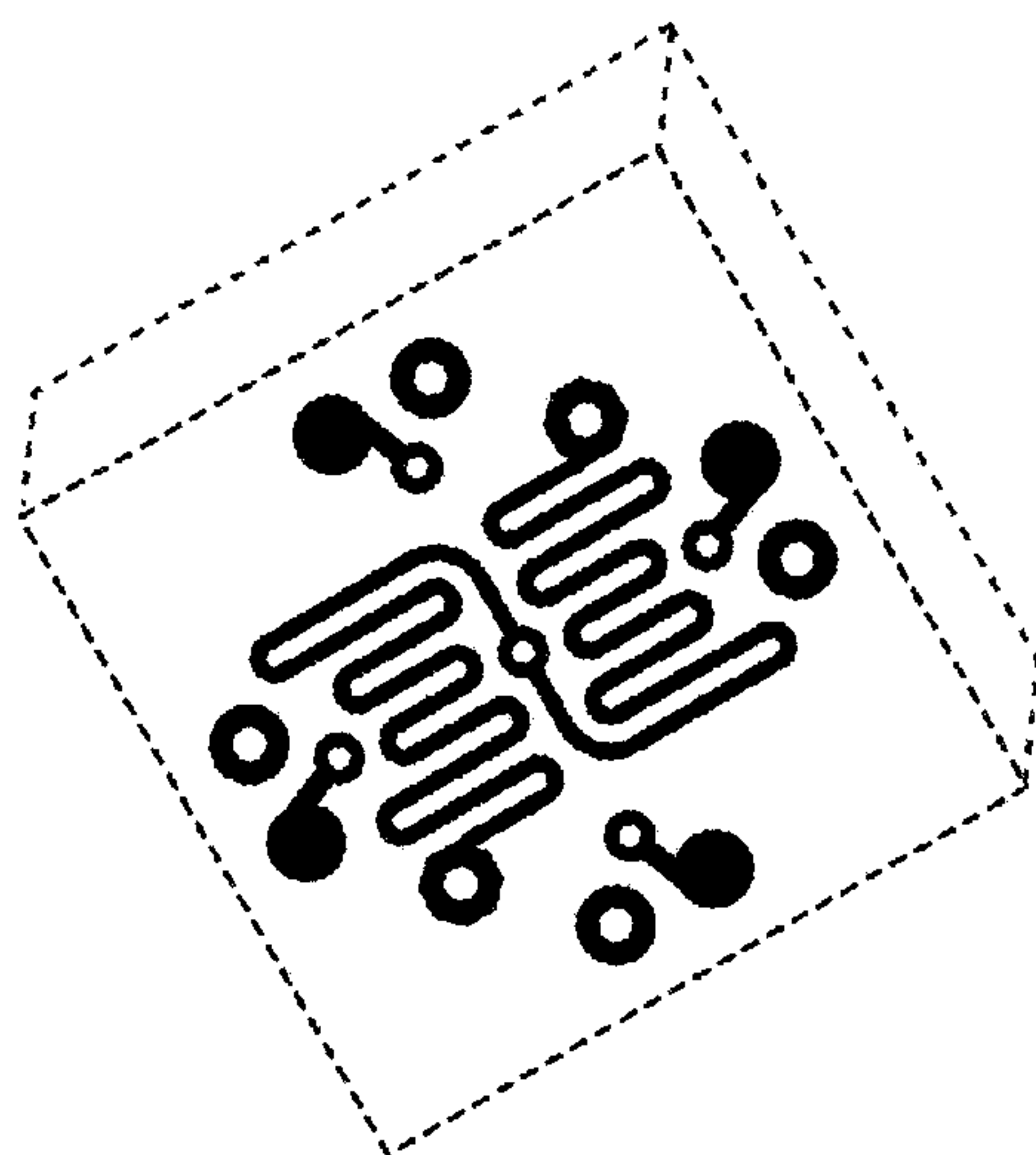
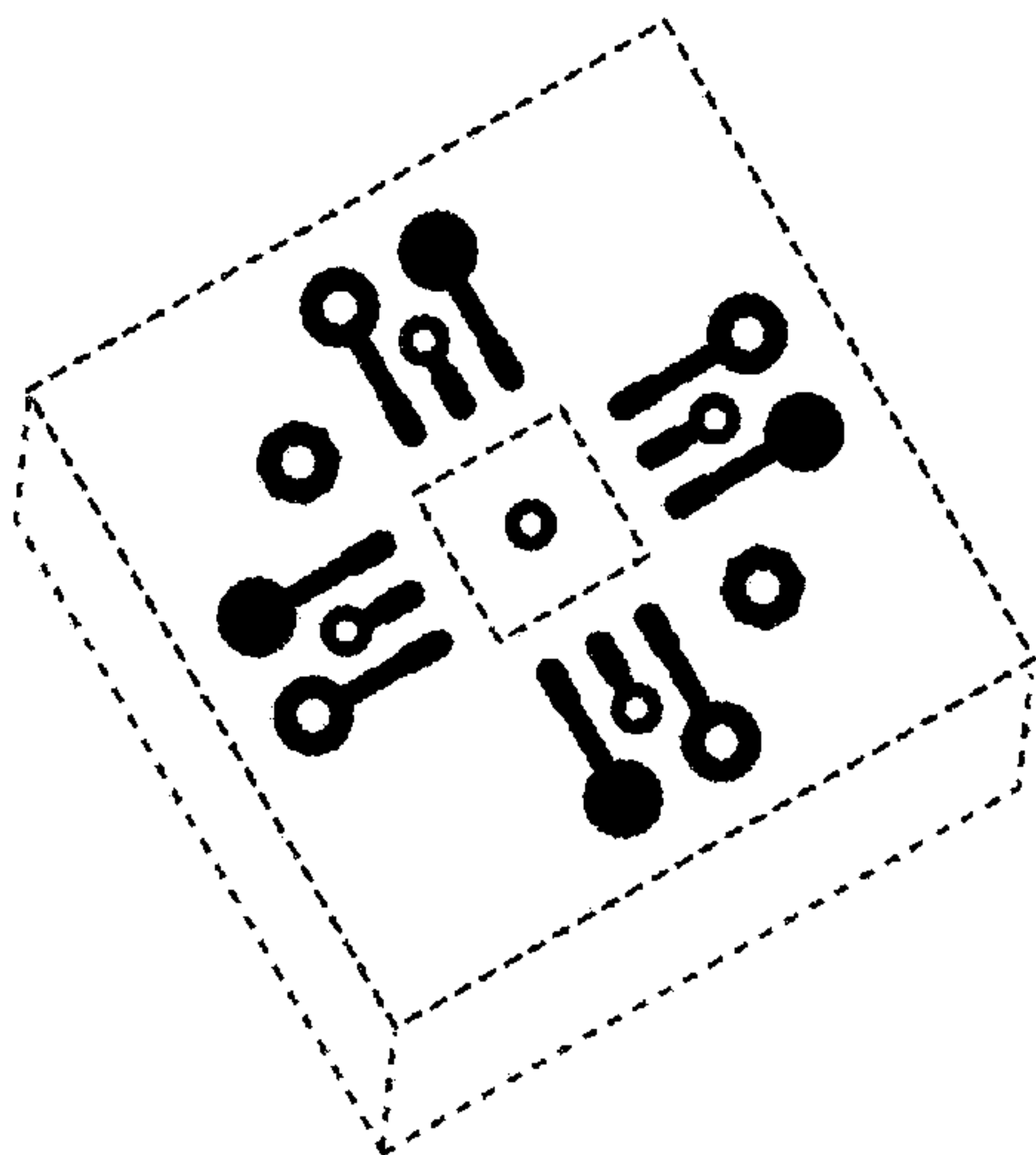
DESCRIPTION

FIG. 1 is a top perspective view of a modular circuit board, showing my new design;
FIG. 2 is a bottom perspective view thereof;
FIG. 3 is a top view thereof;
FIG. 4 is a bottom view thereof; and,
FIG. 5 is a side view thereof, all other side views being a mirror image thereof.
The broken lines shown in the drawings represent portions of the modular circuit board that form no part of the claimed design.

1 Claim, 5 Drawing Sheets

(56) **References Cited**
U.S. PATENT DOCUMENTS

- 2,896,033 A * 7/1959 Hartz H01H 19/585
200/11 D
- 3,072,734 A * 1/1963 Fox H02B 1/043
174/254
- D279,670 S * 7/1985 Lukits D13/182
- 4,602,271 A * 7/1986 Dougherty, Jr. H01L 23/5385
257/697



(56)

References Cited

U.S. PATENT DOCUMENTS

D474,773 S * 5/2003 Kondo D13/182
 D485,536 S * 1/2004 Dang D13/182
 6,936,916 B2 * 8/2005 Moxham H01L 23/13
 174/256
 D552,048 S * 10/2007 He D13/182
 D556,158 S * 11/2007 Kong D13/182
 7,511,228 B2 3/2009 Yaung et al.
 D599,308 S * 9/2009 Blumberg, Jr. D13/182
 D605,613 S * 12/2009 Carter D13/182
 D639,756 S * 6/2011 Greene, Jr. D13/182
 D642,546 S * 8/2011 Greene, Jr. D13/182
 D645,039 S * 9/2011 Chen D14/341
 8,113,888 B2 * 2/2012 Carter H01R 9/03
 439/676
 D676,004 S * 2/2013 Lyubachev D13/182
 D699,201 S * 2/2014 Petsch D13/182
 D768,115 S * 10/2016 Kazanchian D13/182
 D794,586 S * 8/2017 Takahashi D13/182
 D799,438 S * 10/2017 Takahashi D13/182
 D804,437 S * 12/2017 Kantor D13/182
 2006/0044765 A1 * 3/2006 Chen H05K 1/0206
 361/720
 2007/0205017 A1 * 9/2007 Takakusaki H05K 3/244
 174/260
 2008/0080151 A1 * 4/2008 Shimizu H05K 1/0263
 361/760
 2009/0250246 A1 10/2009 Yaung et al.
 2009/0268390 A1 * 10/2009 King G06F 13/409
 361/679.33

* cited by examiner

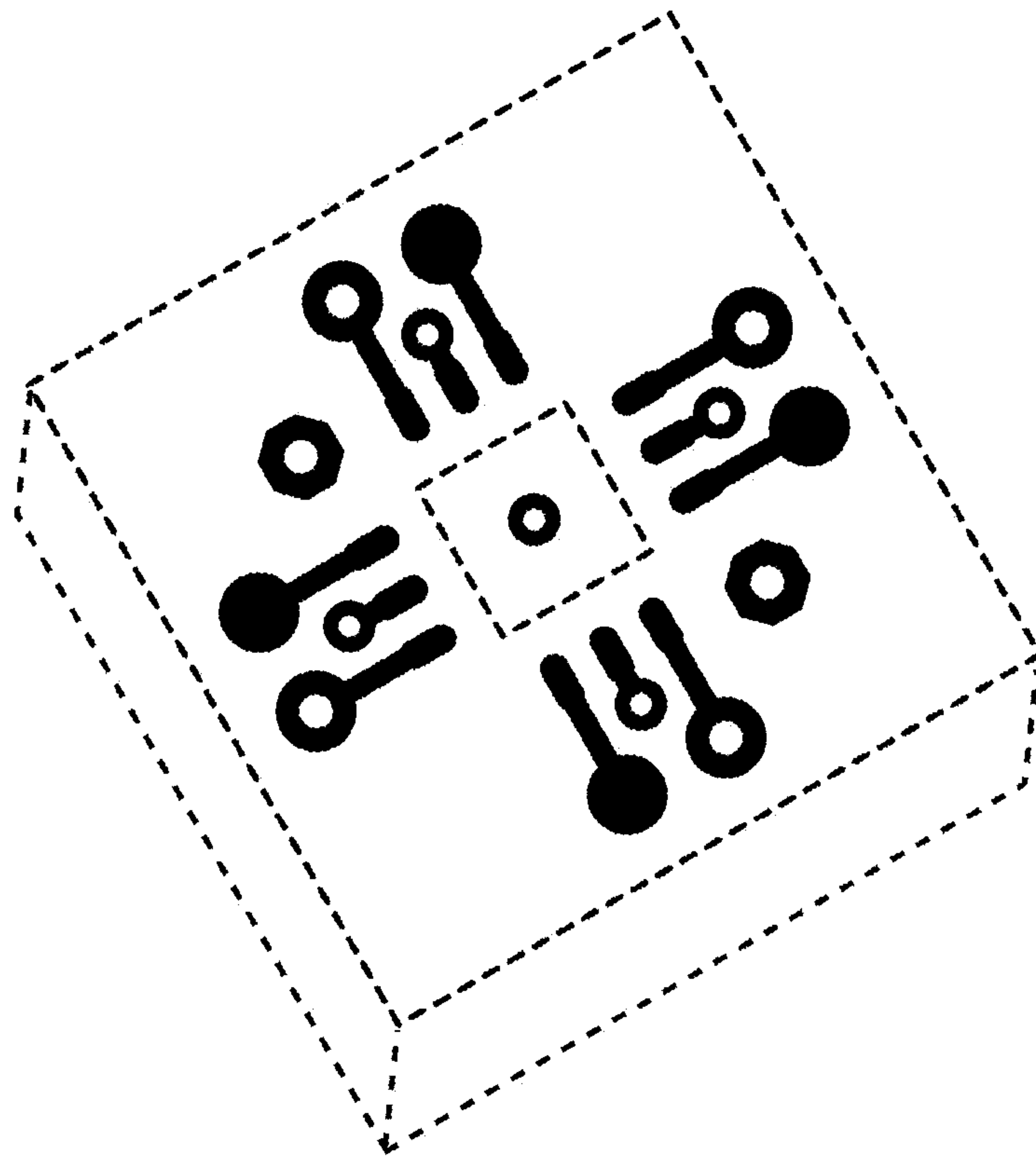


FIG. 1

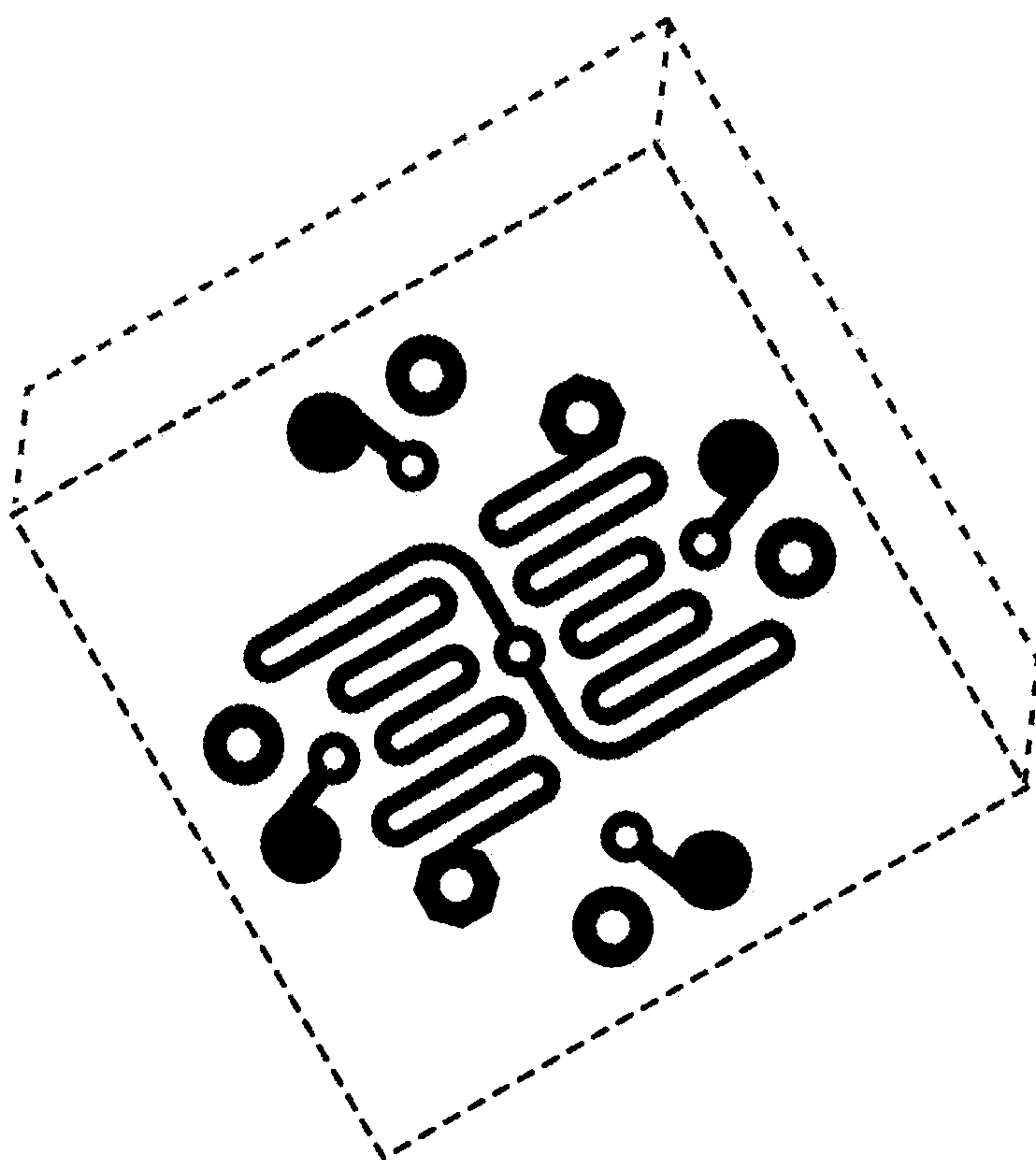


FIG. 2

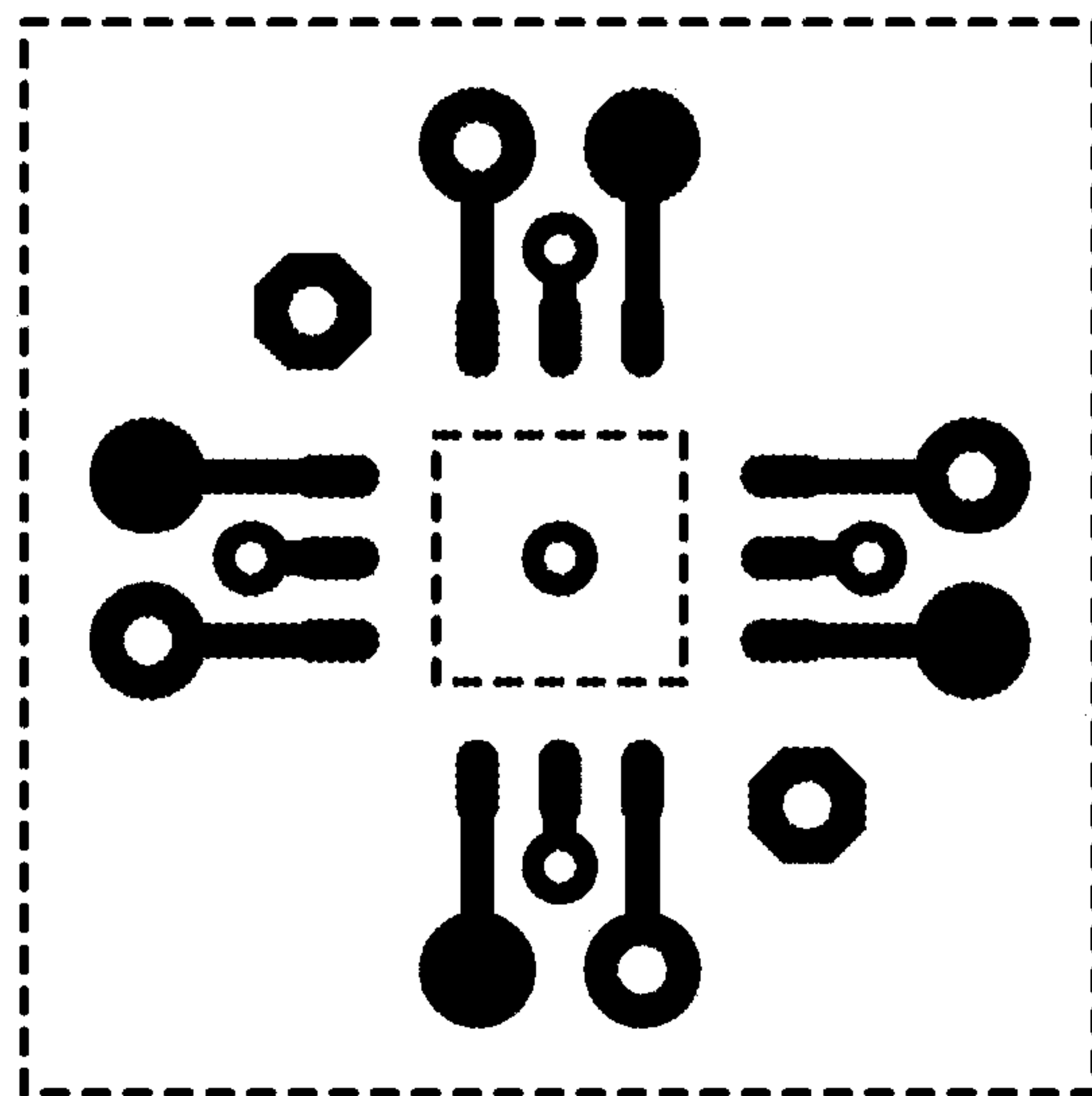


FIG. 3

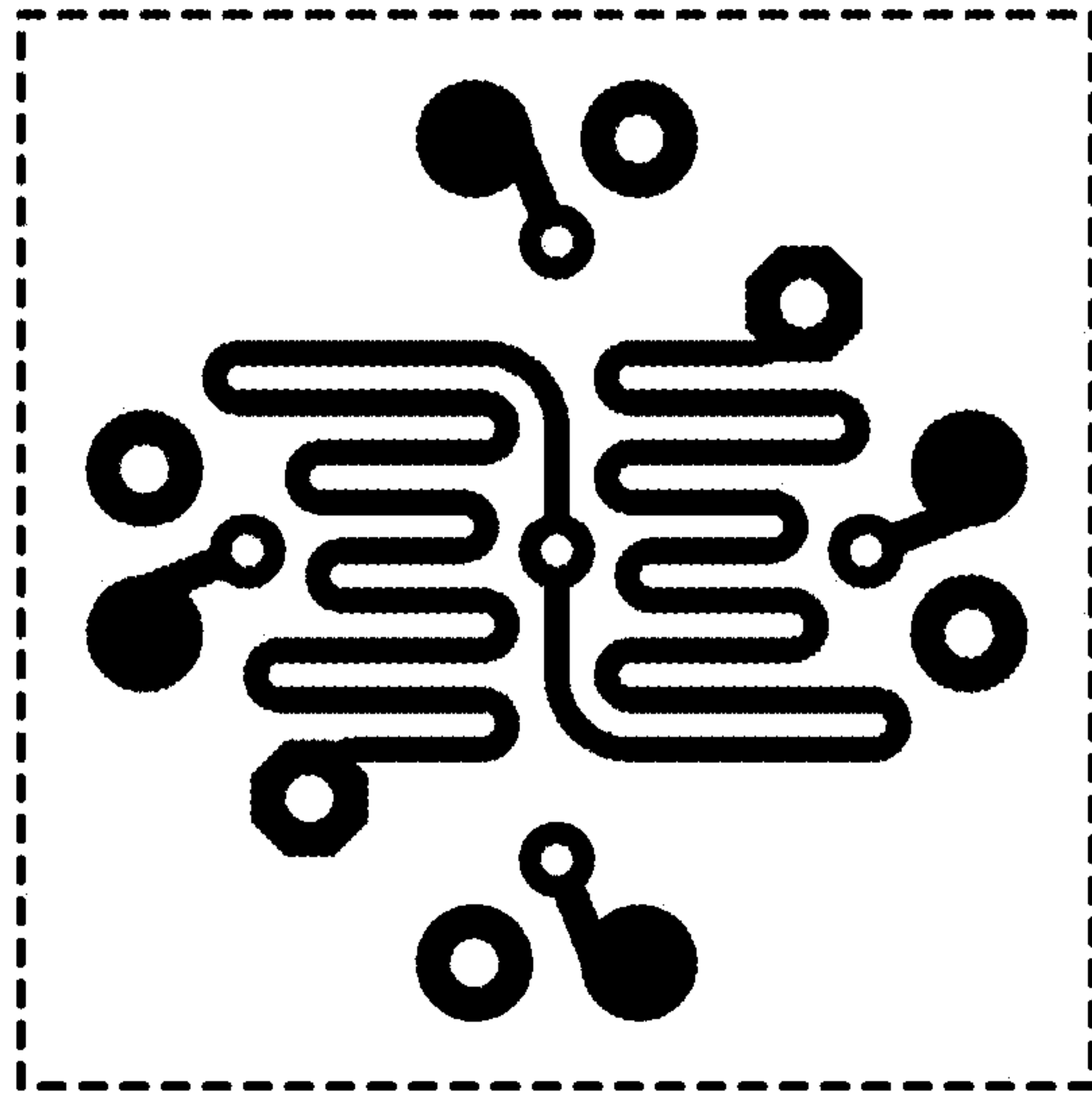


FIG. 4



FIG. 5